imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



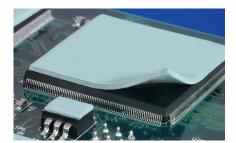
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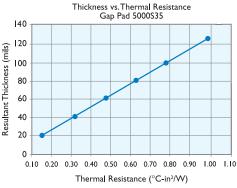
Features and Benefits

- High thermal conductivity: 5 W/m-K
- Highly conformable, "S-Class" softness
- Natural inherent tack reduces interfacial thermal resistance
- Conforms to demanding contours and maintains structural integrity with little or no stress applied to fragile component leads
- Fiberglass reinforced for puncture, shear and tear resistance
- Excellent thermal performance at low pressures



Gap Pad 5000S35 is a fiberglass-reinforced filler and polymer featuring a high thermal conductivity. The material yields extremely soft characteristics while maintaining elasticity and conformability. The fiberglass reinforcement provides easy handling and converting, added electrical isolation and tear resistance. The inherent natural tack on both sides assists in application and allows the product to effectively fill air gaps, enhancing the overall thermal performance. The top side has reduced tack for ease of handling. Gap Pad 5000S35 is ideal for high-performance applications at low mounting pressures.

Note: Resultant thickness is defined as the final gap thickness of the application.



High thermal conductivity plus "S-Class" softness and conformability

TYPICAL PROPERTIES OF GAP PAD 5000S35				
IMPERIAL VALUE	METRIC VALUE		TEST METHOD	
Light Green	Light Green		Visual	
Fiberglass	Fiberglass		_	
0.020 to 0.125	0.508 to 3.175		ASTM D374	
2	2			
3.6	3.6		ASTM D792	
1.0	1.0		ASTM EI269	
35	35		ASTM D2240	
17.5	121		ASTM D575	
-76 to 392	-60 to 200			
>5000	>5000		ASTM D149	
7.5	7.5		ASTM D150	
109	1 O ⁹		ASTM D257	
V-O	V-O		U.L. 94	
5.0	5.0		ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN				
Deflection (%	strain)	10	20	30
Thermal Impedance (°C-in²/W) 0.040" (3) 0.41 0.34 0.30				
	IMPERIAL VALUE Light Green Fiberglass 0.020 to 0.125 2 3.6 1.0 35 17.5 -76 to 392 >5000 7.5 10° V-O 5.0 AIN Deflection (%	IMPERIAL VALUE METRIC VALUE Light Green Light Gr Fiberglass Fibergla 0.020 to 0.125 0.508 to 3 2 2 3.6 3.6 1.0 1.0 35 35 17.5 121 -76 to 392 -60 to 2 >5000 >5000 7.5 7.5 10° 10° V-O V-O 5.0 5.0 AIN 5.0	IMPERIAL VALUE METRIC VALUE Light Green Light Green Fiberglass Fiberglass 0.020 to 0.125 0.508 to 3.175 2 2 3.6 3.6 1.0 1.0 35 35 17.5 121 -76 to 392 -60 to 200 >5000 >5000 7.5 7.5 10° 10° V-O V-O 5.0 5.0 AIN 5.0	IMPERIAL VALUE METRIC VALUE TEST M Light Green Light Green Vis Fiberglass Fiberglass – 0.020 to 0.125 0.508 to 3.175 ASTM 2 2 – 3.6 3.6 ASTM 1.0 1.0 ASTM 35 35 ASTM 17.5 121 ASTM ~76 to 392 -60 to 200 – >5000 >5000 ASTM 10° 10° ASTM 10° 0.10° ASTM 10° 5.0 ASTM 5.0 5.0 ASTM 5.0 5.0 ASTM 4IN – –

1) Thirty second delay value Shore 00 hardness scale. 2)Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

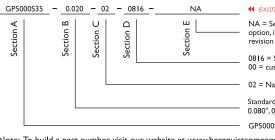
Typical Applications

- CDROM / DVD ROM
- Voltage Regulator Modules (VRMs) and POLs
- Thermally-enhanced BGAs

Configurations Available:

• Die-cut parts are available in any shape or size, separated or in sheet form

Building a Part Number



ASICs and DSPs

• Memory packages / modules

PC Board to chassis

Standard Options

example



GP5000S35 = Gap Pad 5000S35 Material

Note: To build a part number, visit our website at www.bergquistcompany.com.



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